

1-826469-0 ✓ ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 1-826469-0

PCB Mount Header, Vertical, Board-to-Board, 20 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **20**

Number of Rows: **2**

## Features

### Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	20
Number of Rows	2
Board-to-Board Configuration	Parallel

### Electrical Characteristics

Insulation Resistance	5000 M $\Omega$
Dielectric Withstanding Voltage (Max)	750 Vrms

### Body Features

Connector Profile	Standard
Primary Product Color	Black

### Contact Features



PCB Contact Termination Area Plating Material Thickness	3 $\mu$ m
Mating Pin Diameter	.63 mm[.025 in]
Contact Shape & Form	Round
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.8 $\mu$ m[31.5 $\mu$ in]
Contact Type	Pin
Contact Current Rating (Max)	5 A

### Termination Features

Round Termination Post & Tail Diameter	.63 mm[.025 in]
Termination Post & Tail Length	3.2 mm[.126 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

### Mechanical Attachment

Mating Retention	With
Mating Retention Type	Detent Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount

### Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	PCT

### Dimensions

Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]

### Usage Conditions

Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]

### Operation/Application



Solder Process Feature	Board Standoff
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Circuit Application	Signal
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### Industry Standards

Agency/Standard	CSA, UL
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Approved Standards	CSA LR7189, CUL E28476
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UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	200
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Packaging Type	Box
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
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Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
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Solder Process Capability	Pin-in-Paste capable to 260°C
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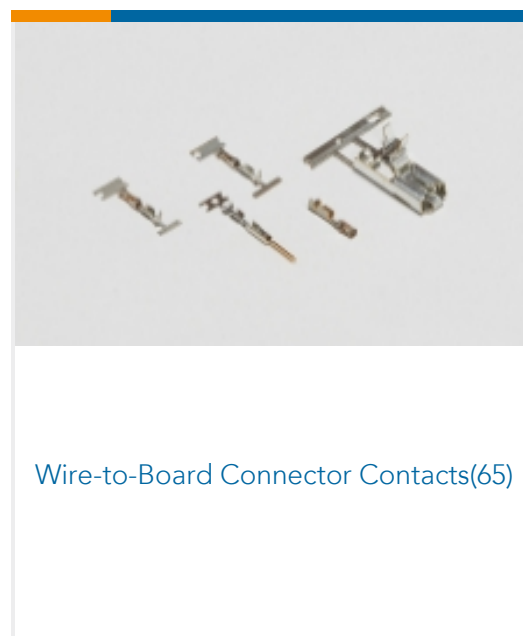
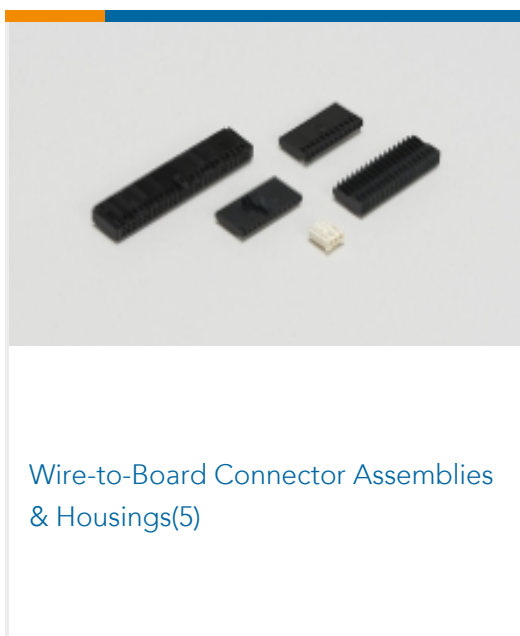
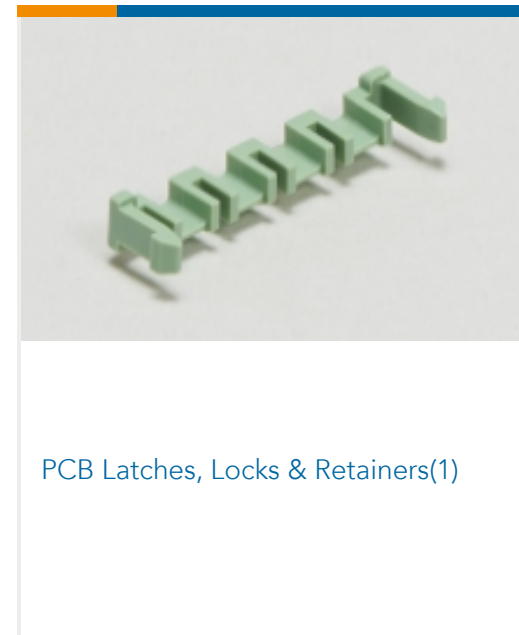
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



## Also in the Series | AMPMODU Headers



## Customers Also Bought





## Documents

### Product Drawings

[2X10P MOD II SHROUDED HEADER, ST](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1-826469-0\\_E.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1-826469-0\\_E.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1-826469-0\\_E.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Environmental Compliance

[Product Compliance](#)

English

[Product Compliance](#)

English

### Agency Approvals

[UL Report](#)

English